

Sumitomo Bakelite Co., Ltd.
October 9, 2026

Expansion of Production Capacity for Advanced Semiconductor Encapsulation Materials in Suzhou, China, and Singapore

Sumitomo Bakelite Co., Ltd. (Headquarters: Shinagawa-ku, Tokyo; President and Representative Director: Shinichi Kajiya) will expand production capacity for encapsulation materials used in advanced semiconductor packages at its sites in Suzhou, China, and Singapore. New production lines will be installed at both sites for SUMIKON™ EME mold underfill (MUF) materials and compression-molding granules.

Background of the Investment to Increase Production

Demand for advanced semiconductors used in applications such as generative AI and communications satellites is growing rapidly, particularly in China and Southeast Asia. At the same time, semiconductor packages are becoming increasingly dense, thin, and large.

Our MUF materials provide excellent filling performance in microscopic gaps and low-warpage characteristics. By filling solder joints and encapsulating the entire package in a single molding process, they deliver both high reliability and manufacturing efficiency.

Our compression-molding granules also provide excellent filling performance in narrow gaps. By optimally controlling filler size, resin viscosity, and particle-size distribution, they enable uniform molding and low warpage even for large panels, thereby improving productivity in advanced semiconductor manufacturing. To leverage the strengths of these products and technologies and respond promptly and reliably to growing demand, we will expand production capacity in Suzhou, China, and Singapore.



SUMIKON™ EME

Details of the Investment to Increase Production

(1) Sumitomo Bakelite (Suzhou) Co., Ltd. (Suzhou, China)

We will expand the facilities at the new plant, which was completed in 2024, and install new production lines for MUF materials and compression-molding granules. Production is scheduled to begin in fiscal 2030.

(2) Sumitomo Bakelite Singapore Pte. Ltd. (Singapore)

We will install new production lines for MUF materials and compression-molding granules within the existing plant. Production is scheduled to begin at the end of fiscal 2028.

Following this production capacity expansion, production capacity for MUF materials is expected to approximately double, while capacity for compression-molding granules is expected to approximately triple, compared with current levels. In addition, through the planned acquisition of Kyocera Corporation's chemical business at the end of October, the Group will add Kyocera's production capacity for MUF materials and compression-molding granules. Together, these initiatives will further strengthen the Group's supply capabilities in major advanced semiconductor manufacturing regions, including Japan, China, and Southeast Asia.

Through these production capacity investments and the planned business acquisition, the Group will strengthen its global supply system for advanced semiconductor encapsulation materials. By reliably capturing growing demand, we aim to drive business growth and expand our market share.

Sumitomo Bakelite (Suzhou) Co., Ltd.

Location: Suzhou, Jiangsu, China

Year Established: 1997

Site Area: Approximately 60,000 m²

Main Products: Epoxy molding compounds for semiconductor encapsulation and die-bonding paste



Sumitomo Bakelite Singapore Pte. Ltd.

Location: Senoko South Road, Singapore

Year Established: 1982

Site area: Approximately 22,500 m²

Main Products: Epoxy molding compounds for semiconductor encapsulation and die-bonding paste



For inquiries regarding this matter:

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